

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Express Mail label number under 37 C.F.R. § 1.10:
EJ502271574US

In re the Application of

Potts (TI-27832)

Serial No.: not assigned

Filed: Herewith

For: Semiconductor Wafer With Grouped Integrated Circuit Die Having Inter-Die Connections For Group Testing

PRELIMINARY AMENDMENT

Commissioner for Patents

Washington, DC 20231

Dear Sir:

Applicant respectfully requests amendment of the specification of the above-referenced application, prior to its examination, as follows:

In the Specification:

On page 1, please replace the paragraph [0001], from lines 4 through 6, with the following, and the replaced paragraph is also shown in re-written form, with underlining showing additions and brackets showing deletions, on a sheet attached to this Amendment and filed herewith:

[0001] This application claims the benefit, under 35 U.S.C. §119(e)(1), of U.S. Provisional Application No. 60/344,161 (TI-27832PS), filed December 27, 2001, and incorporated herein by this reference.

REMARKS

Amendment of the above-referenced application as described above is respectfully requested in order to complete the priority claim on the first page of the application.

Respectfully submitted,



Stephen L. Levine
Registry No. 33,413
Attorney for Applicant

Version with markings to show changes made:

[0001] This application claims the benefit, under 35 U.S.C. §119(e)(1), of U.S. Provisional Application No. 60/344,161 [] (TI-27832PS), filed December 27, 2001, and incorporated herein by this reference.

2001-01-01 10:00:00